SENTECH INTERNATIONAL AG PROTECTION PRODUCTS

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20µs)	P _{pk}	350	Watts
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	25 20	kV
Operating Temperature	T,	-55 to +125	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Electrical Characteristics

SMS05									
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units			
Reverse Stand-Off Voltage	V _{RWM}				5	V			
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA	6			V			
Reverse Leakage Current	I _R	V _{RWM} = 5V, T=25°C			20	μA			
Clamping Voltage	V _c	I _{pp} = 5A, t _p = 8/20μs			9.8	V			
Clamping Voltage	V _c	$I_{pp} = 24A, t_p = 8/20\mu s$			14.5	V			
Peak Pulse Current	I _{PP}	t _p = 8/20μs			24	А			
Junction Capacitance	C _j	Between I/O Pins and Ground V _R = OV, f = 1MHz		325	400	pF			

SMS12									
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units			
Reverse Stand-Off Voltage	V _{RWM}				12	V			
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA	13.3			V			
Reverse Leakage Current	I _R	V _{RWM} = 12V, T=25°C			1	μA			
Clamping Voltage	V _c	$I_{pp} = 5A, t_p = 8/20 \mu s$			19	V			
Clamping Voltage	V _c	I _{pp} = 15Α, t _p = 8/20μs			23	V			
Peak Pulse Current	I _{PP}	t _p = 8/20μs			15	А			
Junction Capacitance	C _j	Between I/O Pins and Ground V _R = OV, f = 1MHz		135	150	pF			

SEMITECH INTERNATIONAL AG PROTECTION PRODUCTS

SMS05 through SMS24

Electrical Characteristics (Continued)

SMS15

311313						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}				15	V
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA	16.7			V
Reverse Leakage Current	I _R	V _{RWM} = 15V, T=25°C			1	μΑ
Clamping Voltage	V _c	$I_{pp} = 5A, t_p = 8/20 \mu s$			24	V
Clamping Voltage	V _c	I _{pp} = 12Α, t _p = 8/20μs			29	V
Peak Pulse Current	I _{PP}	t _p = 8/20µs			12	А
Junction Capacitance	C _j	Between I/O Pins and Ground V _R = OV, f = 1MHz		100	125	рF

SMS24									
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units			
Reverse Stand-Off Voltage	V _{RWM}				24	V			
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA	26.7			V			
Reverse Leakage Current	I _R	V _{RWM} = 24V, T=25°C			1	μA			
Clamping Voltage	V _c	$I_{pp} = 5A, t_p = 8/20 \mu s$			40	V			
Clamping Voltage	V _c	$I_{pp} = 8A, t_p = 8/20 \mu s$			44	V			
Peak Pulse Current	I _{PP}	t _p = 8/20µs			8	А			
Junction Capacitance	C _j	Between I/O Pins and Ground V _R = OV, f = 1MHz		60	75	pF			



Non-Repetitive Peak Pulse Power vs. Pulse Time







Forward Voltage vs. Forward Current





Clamping Voltage vs. Peak Pulse Current





Applications Information

Device Connection for Protection of Four Data Lines

The SMSxx is designed to protect up to four unidirectional data lines. The device is connected as follows:

 Unidirectional protection of four I/O lines is achieved by connecting pins 1, 3, 4 and 6 to the data lines. Pin 2 and 5 are connected to ground. The ground connections should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces.

Circuit Board Layout Recommendations for Suppression of ESD

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

- Place the SMSxx near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the SMSxx and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

Matte Tin Lead Finish

Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.





Protection of Four Unidirectional Lines





Outline Drawing -SOT23 6L



Land Pattern -SOT23 6L



SEMTECH INTERNATIONAL AG PROTECTION PRODUCTS

Marking Codes

Part Number	Marking Code
SMS05	05\90
SMS12	12\71
SMS15	15\9L
SMS24	24\77

Ordering Information

Part Number	Working Voltage	Qty per Reel	Reel Size
SMS05.TCT	5V	3,000	7 Inch
SMS12.TCT	12V	3,000	7 Inch
SMS15.TCT	15V	3,000	7 Inch
SMS24.TCT	24V	3,000	7 Inch

Tape and Reel Specification



ONLY INCLUDING DRAFT AND RADII CONCENTRIC AROUND B₀

USER DIRECTION OF FEED



User Direction of feed

AO	BO	КО	
3.23 +/-0.05 mm	3.17 +/-0.05 mm	1.37 +/-0.05 mm	

Tape Width	B, (Max)	D	D1	E	F	K (MAX)	Ρ	PO	P2	T(MAX)	W
8 mm	4.2 mm (.165)	1.5 + 0.1 mm - 0.0 mm	1.0 mm ±0.05	1.750±.10 mm	3.5±0.05 mm	2.4 mm	4.0±0.1 mm	4.0±0.1 mm	2.0±0.05 mm	0.4 mm	8.0 mm + 0.3 mm - 0.1 mm

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